Microchip Technology - PIC16LC770/SS Datasheet

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	15
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 6x12b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc770-ss

TABLE 3-3: PORTB FUNCTIONS

Name	Function	Input Type	Output Type	Description
RB0/AN4/INT	RB0	TTL	CMOS	Bi-directional I/O(1)
	AN4	AN		A/D input
	INT	ST		Interrupt input
RB1/AN5/$\overline{\text{SS}}$	RB1	TTL	CMOS	Bi-directional I/O(1)
	AN5	AN		A/D input
	$\overline{\text{SS}}$	ST		SSP slave select input
RB2/SCK/SCL	RB2	TTL	CMOS	Bi-directional I/O(1)
	SCK	ST	CMOS	Serial clock I/O for SPI
	SCL	ST	OD	Serial clock I/O for I^2C
RB3/CCP1/P1A	RB3	TTL	CMOS	Bi-directional I/O(1)
	CCP1	ST	CMOS	Capture 1 input/Compare 1 output
	P1A		CMOS	PWM P1A output
RB4/SDI/SDA	RB4	TTL	CMOS	Bi-directional I/O(1)
	SDI	ST		Serial data in for SPI
	SDA	ST	OD	Serial data I/O for I^2C
RB5/SDO/P1B	RB5	TTL	CMOS	Bi-directional I/O(1)
	SDO		CMOS	Serial data out for SPI
	P1B		CMOS	PWM P1B output
RB6/T1OSO/T1CKI/P1C	RB6	TTL	CMOS	Bi-directional I/O(1)
	T1OSO		XTAL	Crystal/Resonator
	T1CKI	CMOS		TMR1 clock input
	P1C		CMOS	PWM P1C output
RB7/T1OSI/P1D	RB7	TTL	CMOS	Bi-directional I/O(1)
	T1OSI	XTAL		TMR1 crystal/resonator
	P1D		CMOS	PWM P1D output

Note 1: Bit programmable pull-ups.

TABLE 3-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
06h, 106h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xx11	uuuu uu11
86h, 186h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
81h, 181h	OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
95h	WPUB	PORTB Weak Pull-up Control								1111 1111	1111 1111
96h	IOCB	PORTB Interrupt on Change Control								1111 0000	1111 0000
9Dh	ANSEL	—	—	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	--11 1111	--11 1111

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

FIGURE 9-5: SPI SLAVE MODE WAVEFORM (CKE = 0)

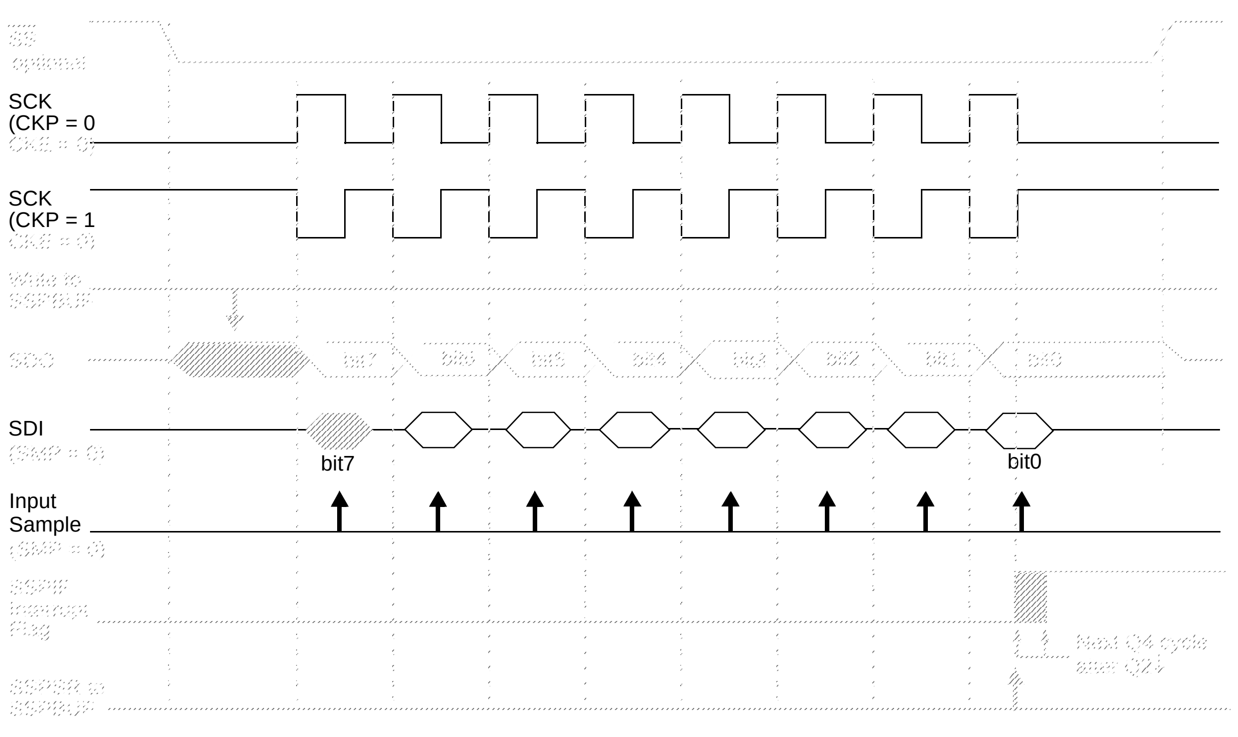


FIGURE 9-6: SPI SLAVE MODE WAVEFORM (CKE = 1)

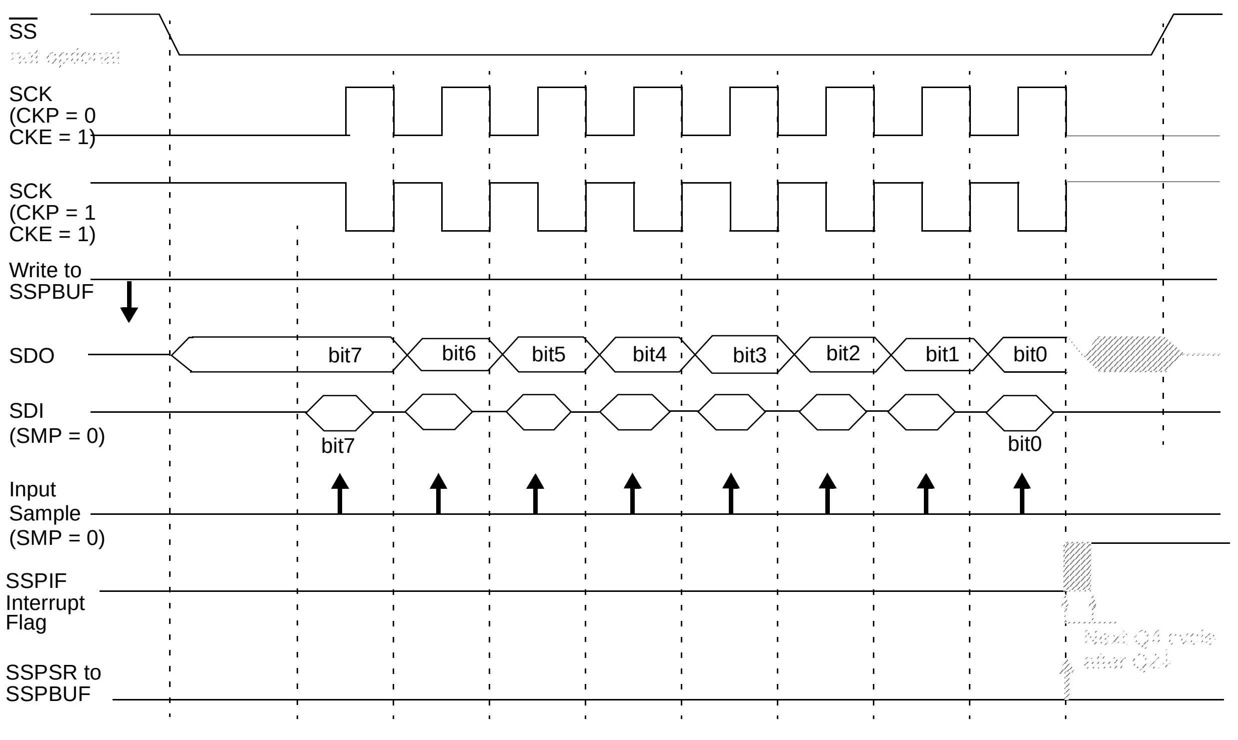
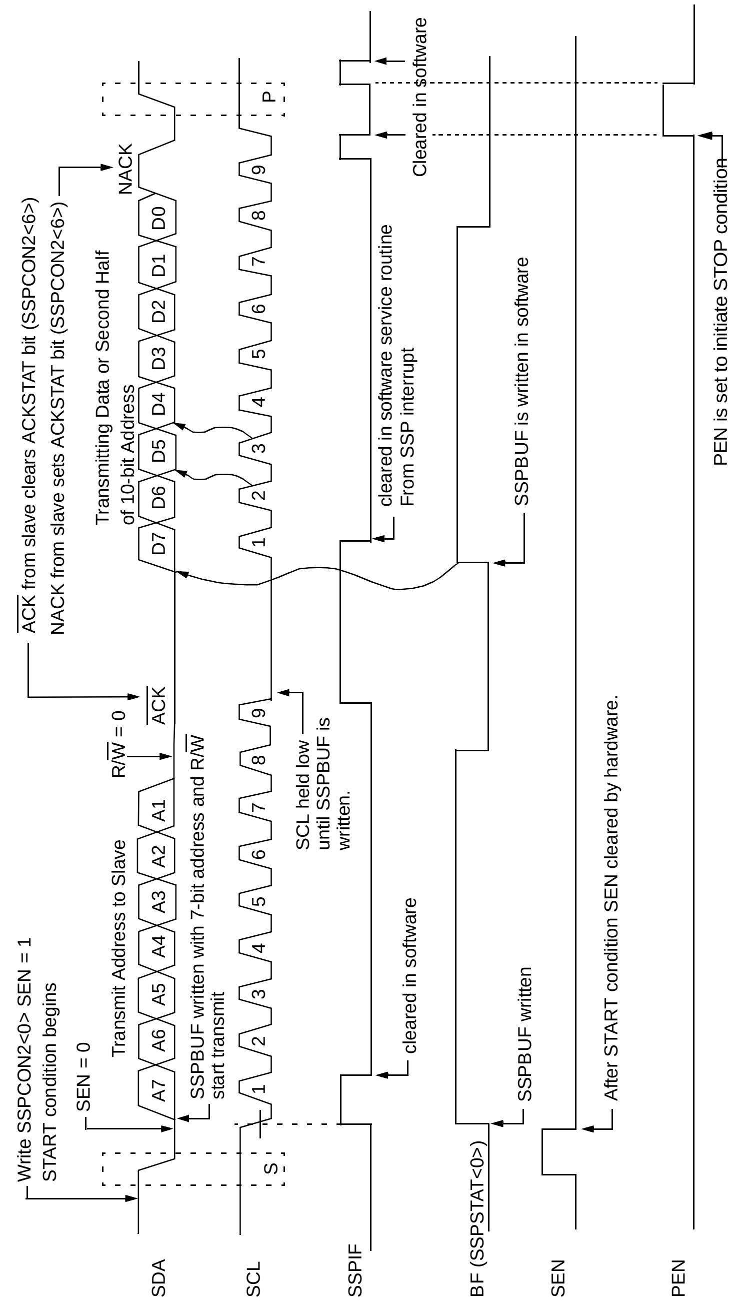


FIGURE 9-18: I²C MASTER MODE WAVEFORMS FOR TRANSMISSION (7 OR 10-BIT ADDRESS)



9.2.17.1 BUS COLLISION DURING A START CONDITION

During a START condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the START condition (Figure 9-24).

b) SCL is sampled low before SDA is asserted low. (Figure 9-25).

During a START condition both the SDA and the SCL pins are monitored.

If:

the SDA pin is already low
or the SCL pin is already low,

then:

the START condition is aborted,
and the BCLIF flag is set,
and the SSP module is reset to its IDLE state (Figure 9-24).

The START condition begins with the SDA and SCL pins de-asserted. When the SDA pin is sampled high, the baud rate generator is loaded from SSPADD<6:0> and counts down to 0. If the SCL pin is sampled low while SDA is high, a bus collision occurs, because it is assumed that another master is attempting to drive a data '1' during the START condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 9-26). If however a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The baud rate generator is then reloaded and counts down to 0, and during this time, if the SCL pin is sampled as '0', a bus collision does not occur. At the end of the BRG count the SCL pin is asserted low.

Note: The reason that bus collision is not a factor during a START condition is that no two bus masters can assert a START condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision, because the two masters must be allowed to arbitrate the first address following the START condition. If the address is the same, arbitration must be allowed to continue into the data portion, REPEATED START or STOP conditions.

FIGURE 9-24: BUS COLLISION DURING START CONDITION (SDA ONLY)

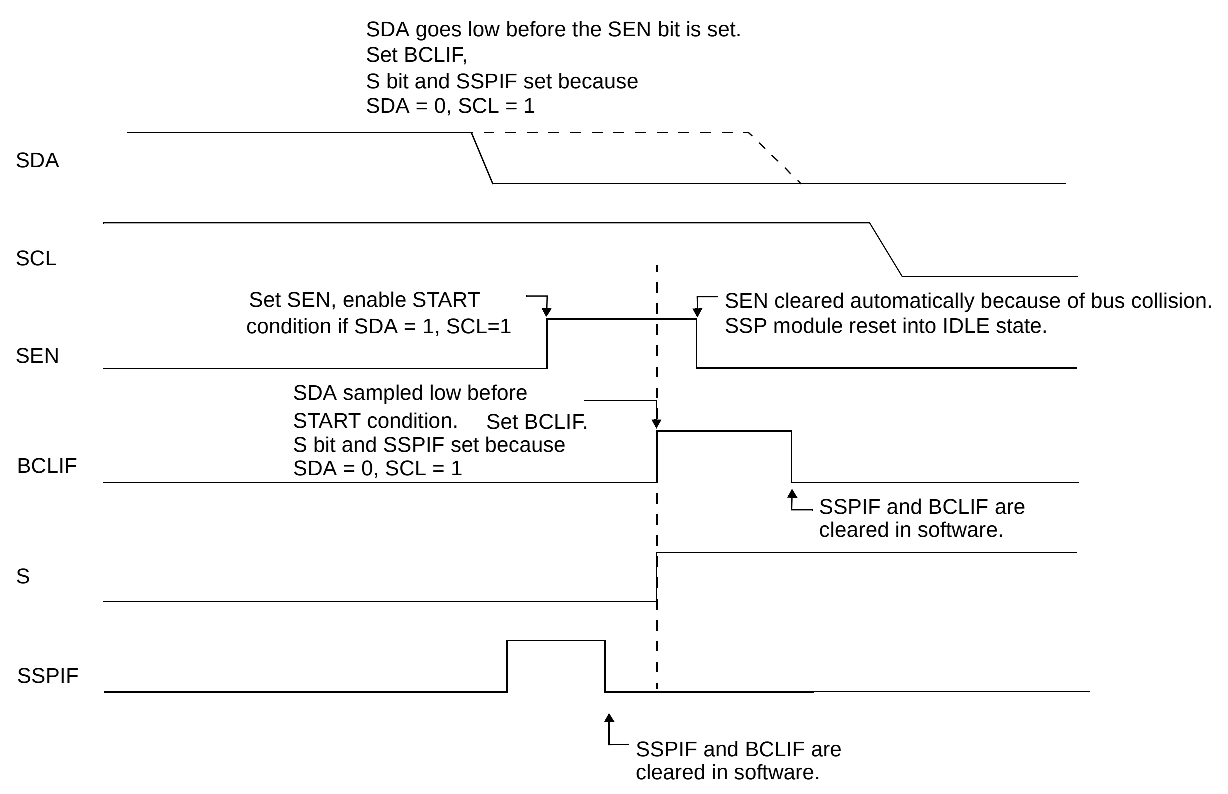


FIGURE 9-25: BUS COLLISION DURING START CONDITION (SCL = 0)

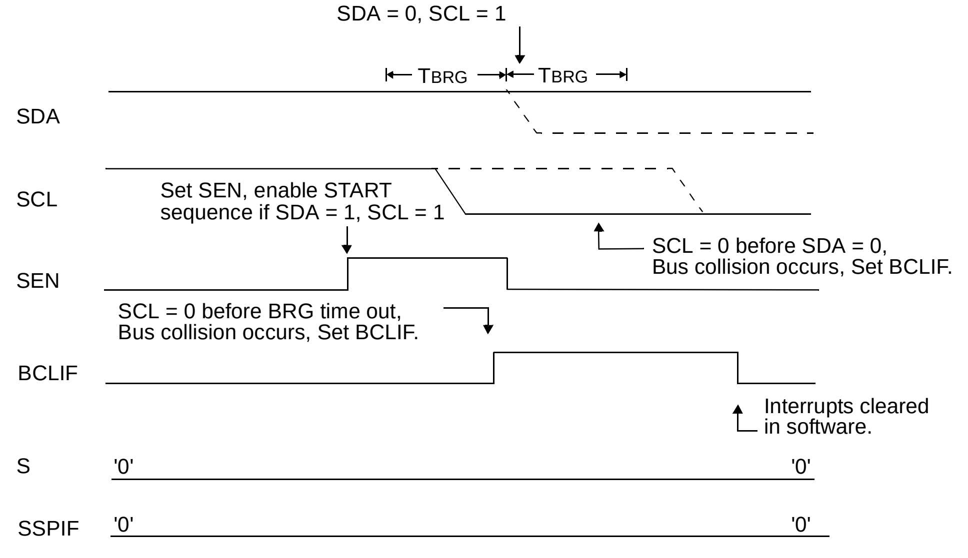
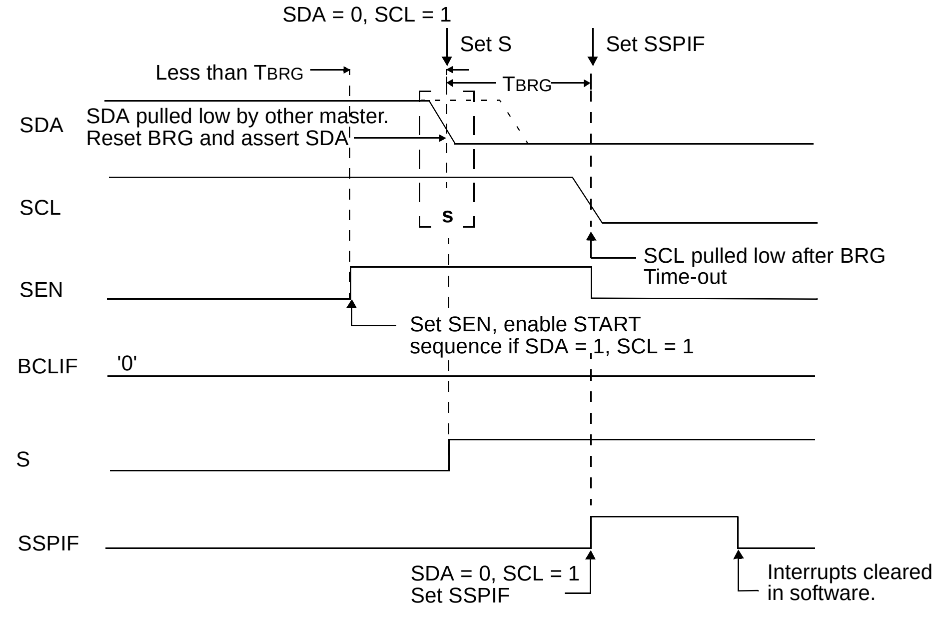


FIGURE 9-26: BRG RESET DUE TO SDA COLLISION DURING START CONDITION



9.2.17.3 BUS COLLISION DURING A STOP CONDITION

Bus collision occurs during a STOP condition if:

a) After the SDA pin has been de-asserted and allowed to float high, SDA is sampled low after the BRG has timed out.

b) After the SCL pin is de-asserted, SCL is sampled low before SDA goes high.

The STOP condition begins with SDA asserted low. When SDA is sampled low, the SCL pin is allowed to float. When the pin is sampled high (clock arbitration), the baud rate generator is loaded with SSPADD<6:0> and counts down to ‘0’. After the BRG times out SDA is sampled. If SDA is sampled low, a bus collision has occurred. This is due to another master attempting to drive a data '0' (Figure 9-29). If the SCL pin is sampled low before SDA is allowed to float high, a bus collision occurs. This is another case of another master attempting to drive a data '0' (Figure 9-30).

FIGURE 9-29: BUS COLLISION DURING A STOP CONDITION (CASE 1)

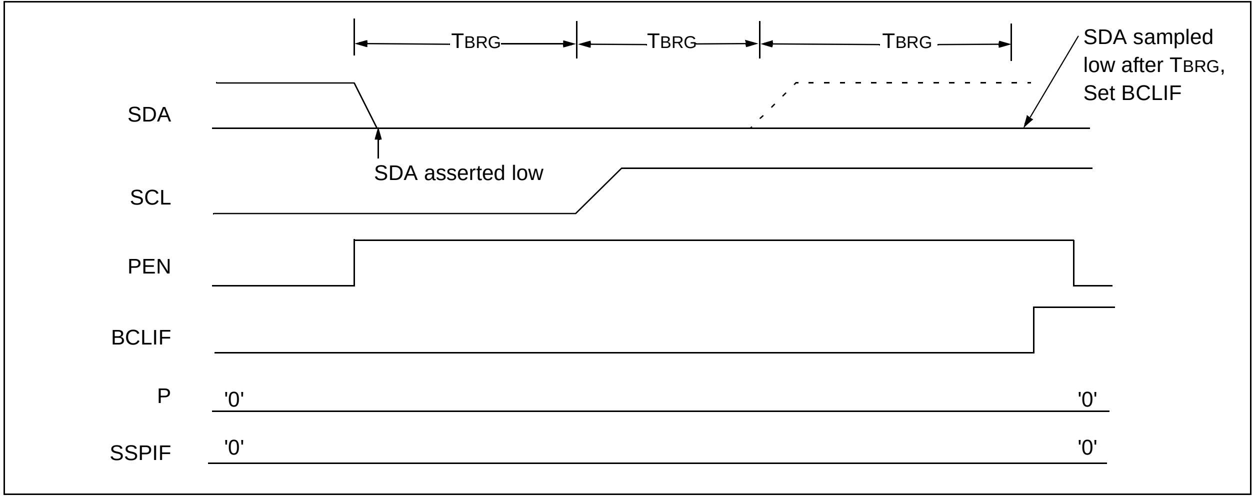
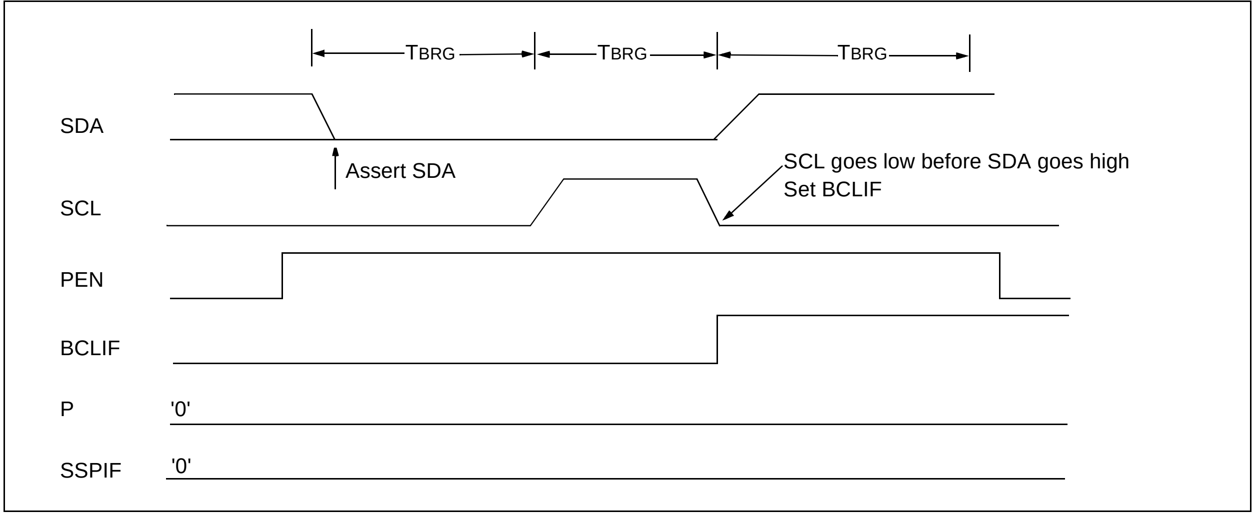


FIGURE 9-30: BUS COLLISION DURING A STOP CONDITION (CASE 2)



9.2.18 CONNECTION CONSIDERATIONS FOR I^{2}C BUS

For Standard mode I^{2}C bus devices, the values of resistors ***R_p*** and ***R_s*** in Figure 9-31 depends on the following parameters

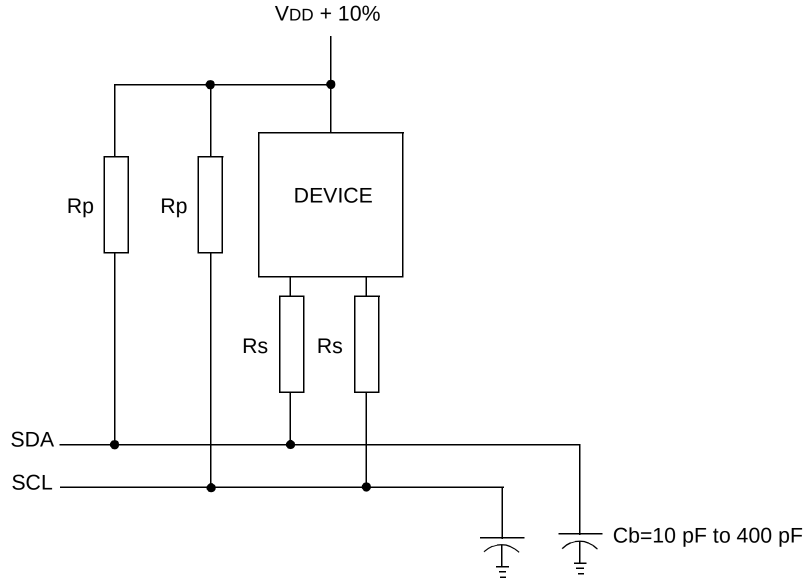
- Supply voltage
- Bus capacitance
- Number of connected devices (input current + leakage current).

The supply voltage limits the minimum value of resistor ***R_p*** due to the specified minimum sink current of 3 mA at VOL max = 0.4V for the specified output stages. For example, with a supply voltage of VDD = 5V±10% and VOL max = 0.4V at 3 mA, $R_{p\ min}$ = (5.5-0.4)/0.003 = 1.7 kΩ. VDD as a function of ***R_p*** is shown in Figure 9-31. The desired noise margin of 0.1VDD for the low level limits the maximum value of ***R_s***. Series resistors are optional and used to improve ESD susceptibility.

The bus capacitance is the total capacitance of wire, connections, and pins. This capacitance limits the maximum value of ***R_p*** due to the specified rise time (Figure 9-31).

The SMP bit is the slew rate control enabled bit. This bit is in the SSPSTAT register, and controls the slew rate of the I/O pins when in I^{2}C mode (master or slave).

FIGURE 9-31: SAMPLE DEVICE CONFIGURATION FOR I^{2}C BUS



Note: I^{2}C devices with input levels related to VDD must have one common supply line to which the pull-up resistor is also connected.

TABLE 9-3: REGISTERS ASSOCIATED WITH I^{2}C OPERATION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	POR, BOR	$\overline{\text{MCLR}}$, WDT
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	`0000 000x`	`0000 000u`
0Ch	PIR1	—	ADIF	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF	`-0-- 0000`	`-0-- 0000`
8Ch	PIE1	—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	`-0-- 0000`	`-0-- 0000`
0Dh	PIR2	LVDIF	—	—	—	BCLIF	—	—	CCP2IF	`0--- 0--0`	`0--- 0--0`
8Dh	PIE2	LVDIE	—	—	—	BCLIE	—	—	CCP2IE	`0--- 0--0`	`0--- 0--0`
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								`xxxx xxxx`	`uuuu uuuu`
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	`0000 0000`	`0000 0000`
91h	SSPCON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	`0000 0000`	`0000 0000`
94h	SSPSTAT	SMP	CKE	D/$\overline{\text{A}}$	P	S	R/$\overline{\text{W}}$	UA	BF	`0000 0000`	`0000 0000`
93h	SSPADD	Synchronous Serial Port (I^{2}C Mode) Address Register								`0000 0000`	`0000 0000`

Legend: `x` = unknown, `u` = unchanged, `-` = unimplemented read as '0'. Shaded cells are not used by the MSSP in I^{2}C mode.

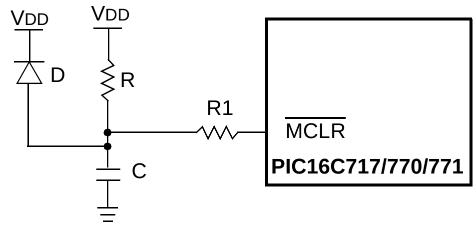
12.4 Power-On Reset (POR)

A Power-on Reset pulse is generated on-chip when a VDD rise is detected (in the range of 1.5V - 2.1V). Enable the internal $\overline{\text{MCLR}}$ feature to eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details. For a long rise time, enable external $\overline{\text{MCLR}}$ function and use circuit as shown in Figure 12-5.

Two delay timers, (PWRT on OST), have been provided which hold the device in RESET after a POR (dependent upon device configuration) so that all operational parameters have been met prior to releasing the device to resume/begin normal operation.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature,...) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met. Brown-out Reset may be used to meet the start-up conditions, or if necessary an external POR circuit may be implemented to delay end of RESET for as long as needed.

FIGURE 12-5: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD RAMP)



Note 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into $\overline{\text{MCLR}}$ from external capacitor C in the event of $\overline{\text{MCLR}}$/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

4: External $\overline{\text{MCLR}}$ must be enabled (MCLRE = 1).

12.5 Power-up Timer (PWRT)

The Power-up Timer provides a fixed TPWRT time-out on power-up type RESETS only. For a POR, the PWRT is invoked when the POR pulse is generated. For a BOR, the PWRT is invoked when the device exits the RESET condition (VDD rises above BOR trip point). The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as the PWRT is active. The PWRT's time delay is designed to allow VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT for the POR only. For a BOR the PWRT is always available regardless of the configuration bit setting.

The power-up time delay will vary from chip-to-chip due to VDD, temperature and process variation. See DC parameters for details.

12.6 Oscillator Start-up Timer (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on a power-up type RESET or a wake-up from SLEEP.

12.7 Programmable Brown-Out Reset (PBOR)

The Programmable Brown-out Reset module is used to generate a RESET when the supply voltage falls below a specified trip voltage. The trip voltage is configurable to any one of four voltages provided by the BORV<1:0> configuration word bits.

Configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below the specified trip point for longer than TBOR, (parameter #35), the brown-out situation will RESET the chip. A RESET may not occur if VDD falls below the trip point for less than TBOR. The chip will remain in Brown-out Reset until VDD rises above VBOR. The Power-up Timer will be invoked at that point and will keep the chip in RESET an additional TPWRT. If VDD drops below VBOR while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above VBOR, the Power-up Timer will again begin a TPWRT time delay. Even though the PWRT is always enabled when brown-out is enabled, the PWRT configuration word bit should be cleared (enabled) when brown-out is enabled.

TABLE 12-6: INITIALIZATION CONDITIONS FOR ALL REGISTERS

Register	Power-on Reset or Brown-out Reset	$\overline{\text{MCLR}}$ Reset or WDT Reset	Wake-up via WDT or Interrupt
W	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	0000 0000	uuuu uuuu	uuuu uuuu
TMR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000h	0000h	PC + 1[1]
STATUS	0001 1xxx	000q quuu[2]	uuuq quuu[2]
FSR	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	xxxx 0000	uuuu 0000	uuuu uuuu
PORTB	xxxx xx11	uuuu uu11	uuuu uuuu
PCLATH	---0 0000	---0 0000	---u uuuu
INTCON	0000 000x	0000 000u	uuuu uuqq
PIR1	-0-- 0000	-0-- 0000	-0-- uuuu
PIR2	0--- 0---	0--- 0---	q--- q---
TMR1L	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	--00 0000	--uu uuuu	--uu uuuu
TMR2	0000 0000	0000 0000	uuuu uuuu
T2CON	-000 0000	-000 0000	-uuu uuuu
SSPBUF	xxxx xxxx	uuuu uuuu	uuuu uuuu
SSPCON	0000 0000	0000 0000	uuuu uuuu
CCPR1L	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1H	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	0000 0000	0000 0000	uuuu uuuu
ADRESH	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	0000 0000	0000 0000	uuuu uuuu
OPTION_REG	1111 1111	1111 1111	uuuu uuuu
TRISA	1111 1111	1111 1111	uuuu uuuu
TRISB	1111 1111	1111 1111	uuuu uuuu
PIE1	-0-- 0000	-0-- 0000	-u-- uuuu
PIE2	0--- 0---	0--- 0---	u--- u---
PCON	---- 1-qq	---- 1-uu	---- u-uu
PR2	1111 1111	1111 1111	1111 1111
SSPADD	0000 0000	0000 0000	uuuu uuuu
SSPSTAT	0000 0000	0000 0000	uuuu uuuu
WPUB	1111 1111	1111 1111	uuuu uuuu
IOCB	1111 0000	1111 0000	uuuu uuuu

Legend: `u` = unchanged, `x` = unknown, `-` = unimplemented bit, read as '0', `q` = value depends on condition

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

2: See Table 12-5 for RESET value for specific condition.

FIGURE 12-7: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO VDD): CASE 1

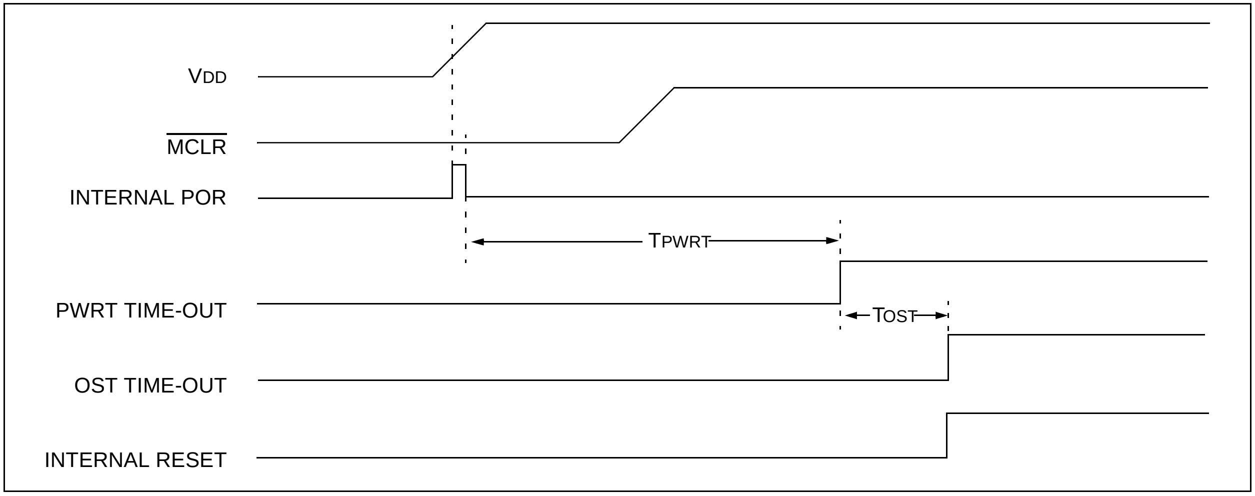


FIGURE 12-8: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO VDD): CASE 2

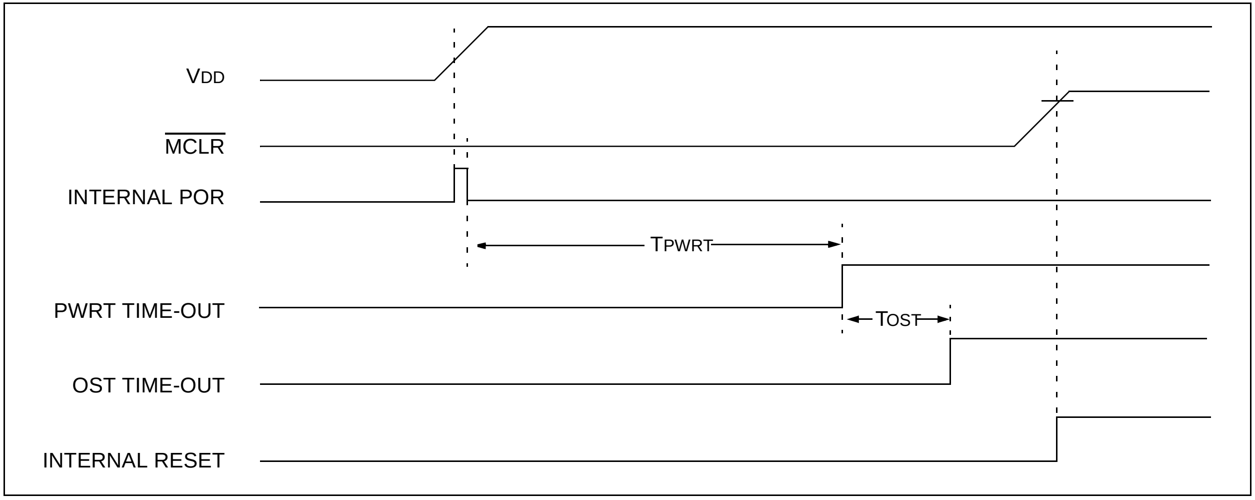
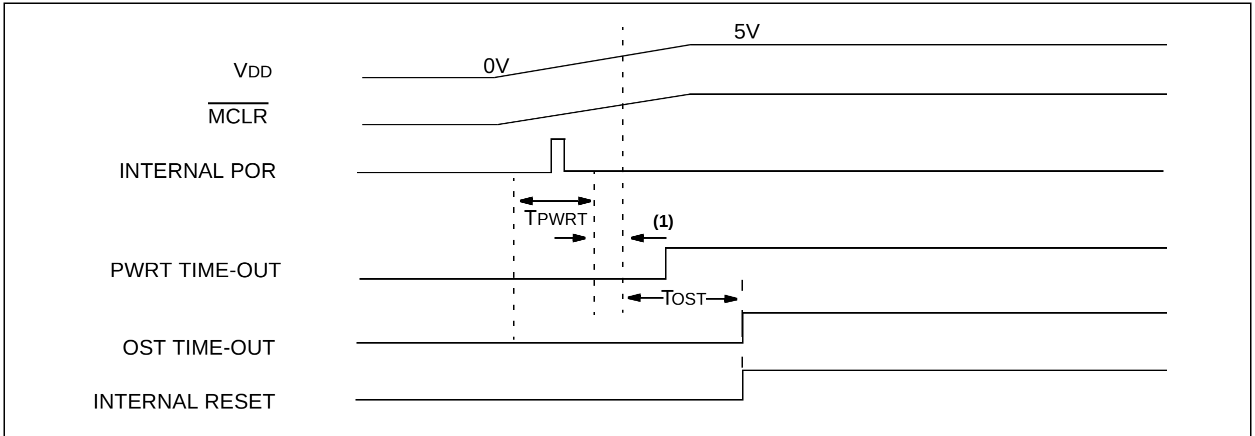


FIGURE 12-9: SLOW VDD RISE TIME ($\overline{\text{MCLR}}$ TIED TO VDD)



Note 1: Time dependent on oscillator circuit

12.10.1 INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered: either rising if bit INTEDG (OPTION_REG<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 12.13 for details on SLEEP mode.

12.10.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>). (Section 2.2.2.3)

12.10.3 PORTB INTCON CHANGE

An input change on PORTB<7:0> sets flag bit RBIF (INTCON<0>). The PORTB pin(s) which can individually generate interrupt is selectable in the IOCB register. The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>). (Section 2.2.2.3)

12.11 Context Saving During Interrupts

During an interrupt, only the PC is saved on the stack. At the very least, W and STATUS should be saved to preserve the context for the interrupted program. All registers that may be corrupted by the ISR, such as PCLATH or FSR, should be saved.

Example 12-1 stores and restores the STATUS, W and PCLATH registers. The register, W_TEMP, is defined in Common RAM, the last 16 bytes of each bank that may be accessed from any bank. The STATUS_TEMP and PCLATH_TEMP are defined in bank 0.

The example:

a) Stores the W register.
b) Stores the STATUS register in bank 0.
c) Stores the PCLATH register in bank 0.
d) Executes the ISR code.
e) Restores the PCLATH register.
f) Restores the STATUS register
g) Restores W.

Note that W_TEMP, STATUS_TEMP and PCLATH_TEMP are defined in the common RAM area (70h - 7Fh) to avoid register bank switching during context save and restore.

EXAMPLE 12-1: Saving STATUS, W, and PCLATH Registers in RAM

```
#define    W_TEMP            0x70
#define    STATUS_TEMP       0x71
#define    PCLATH_TEMP       0x72
    org    0x04              ; start at Interrupt Vector
    MOVWF   W_TEMP           ; Save W register
    MOVF   STATUS,w
    MOVWF  STATUS_TEMP       ; save STATUS
    MOVF   PCLATH,w
    MOVWF  PCLATH_TEMP       ; save PCLATH
    :
    (Interrupt Service Routine)
    :
    MOVF   PCLATH_TEMP,w
    MOVWF  PCLATH
    MOVF   STATUS_TEMP,w
    MOVWF  STATUS
    SWAPF  W_TEMP,f          ;
    SWAPF  W_TEMP,w          ; swapf loads W without affecting STATUS flags
    RETFIE
```

COMF	**Complement f**
Syntax:	[*label*] COMF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	($\bar{f}$) → (destination)
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

DECF	**Decrement f**
Syntax:	[*label*] DECF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

DECFSZ	**Decrement f, Skip if 0**
Syntax:	[*label*] DECFSZ f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination); skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 1, the next instruction is executed. If the result is 0, then a `NOP` is executed instead making it a $2T_{CY}$ instruction.

GOTO	**Unconditional Branch**
Syntax:	[*label*] GOTO k
Operands:	$0 \leq k \leq 2047$
Operation:	k → PC<10:0> PCLATH<4:3> → PC<12:11>
Status Affected:	None
Description:	`GOTO` is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. `GOTO` is a two cycle instruction.

INCF	**Increment f**
Syntax:	[*label*] INCF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination)
Status Affected:	Z
Description:	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

INCFSZ	**Increment f, Skip if 0**
Syntax:	[*label*] INCFSZ f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(f) + 1 → (destination), skip if result = 0
Status Affected:	None
Description:	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 1, the next instruction is executed. If the result is 0, a `NOP` is executed instead making it a $2T_{CY}$ instruction.

14.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC™ In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ® Demonstration Board

14.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows®-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or ‘C’)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

14.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC MCUs.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

14.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI ‘C’ compilers for Microchip’s PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

15.0 ELECTRICAL CHARACTERISTICS

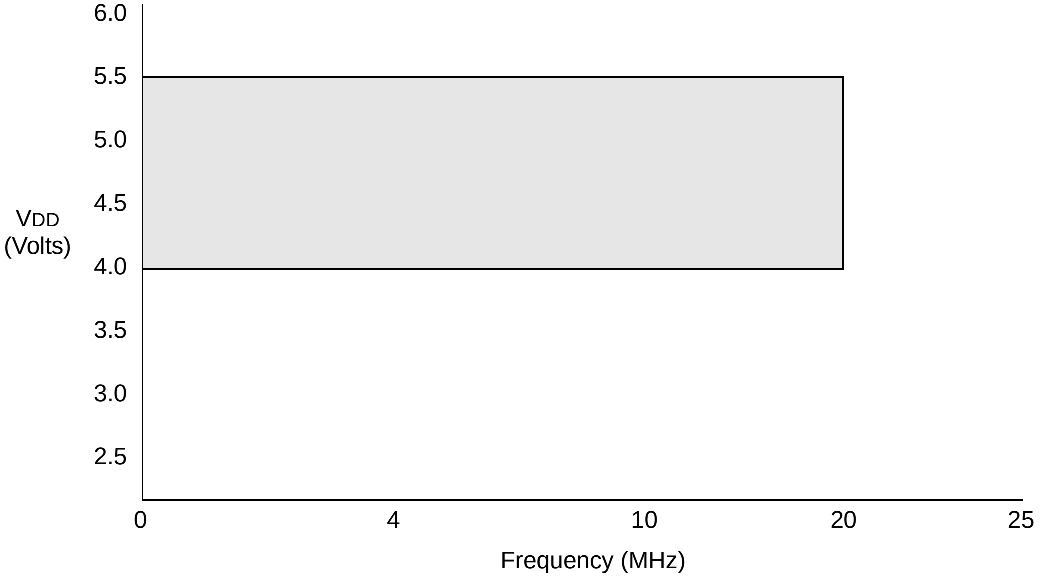
Absolute Maximum Ratings †

Ambient temperature under bias	-55 to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{\text{MCLR}}$ and RA4)	-0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS}	-0.3 to +7.5V
Maximum voltage between AV_{DD} and V_{DD} pins	± 0.3V
Maximum voltage between AV_{SS} and V_{SS} pins	± 0.3V
Voltage on $\overline{\text{MCLR}}$ with respect to V_{SS}	-0.3V to +8.5V
Voltage on RA4 with respect to Vss	-0.3V to +10.5V
Total power dissipation **(Note 1)**	1.0W
Maximum current out of V_{SS} pin	300 mA
Maximum current into V_{DD} pin	250 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	± 20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA and PORTB (combined)	200 mA
Maximum current sourced by PORTA and PORTB (combined)	200 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$.

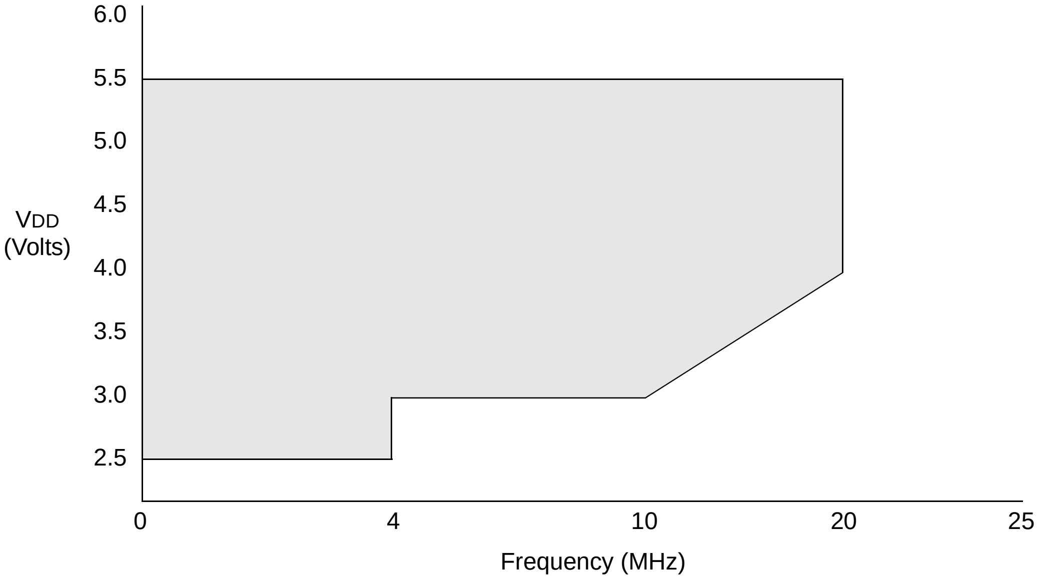
† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 15-1: PIC16C717/770/771 VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ +85°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

FIGURE 15-2: PIC16LC717/770/771 VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

The FOSC IDD was determined using an external sinusoidal clock source with a peak amplitude ranging from VSS to VDD.

FIGURE 16-1: MAXIMUM IDD VS. FOSC OVER VDD (HS MODE)

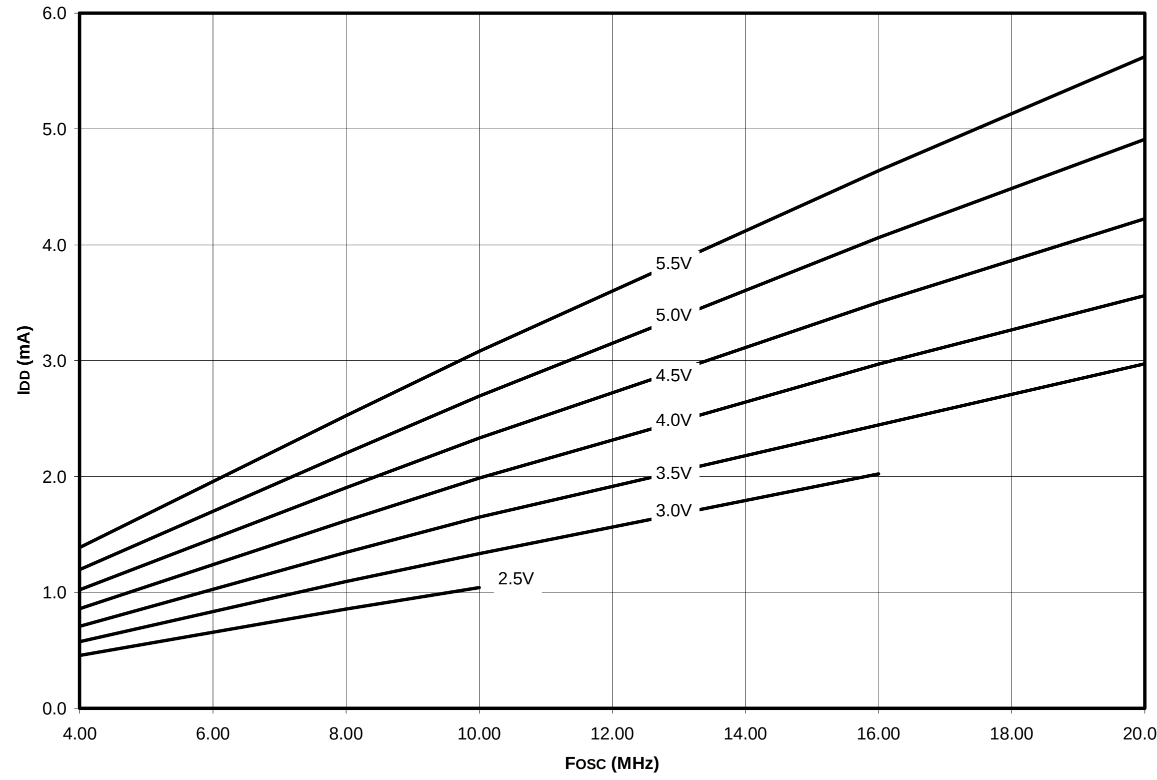


FIGURE 16-2: TYPICAL IDD VS. FOSC OVER VDD (HS MODE)

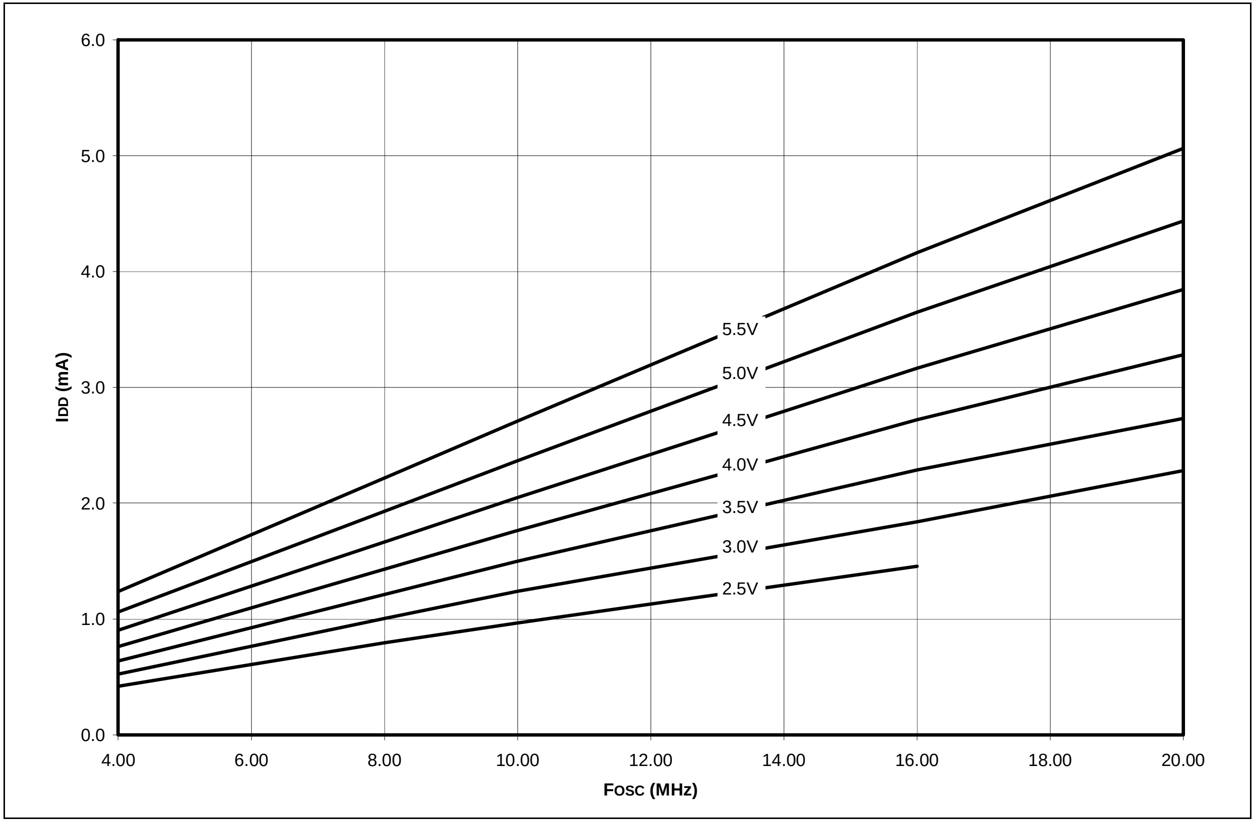


FIGURE 16-3: MAXIMUM IDD VS. FOSC OVER VDD (XT MODE)

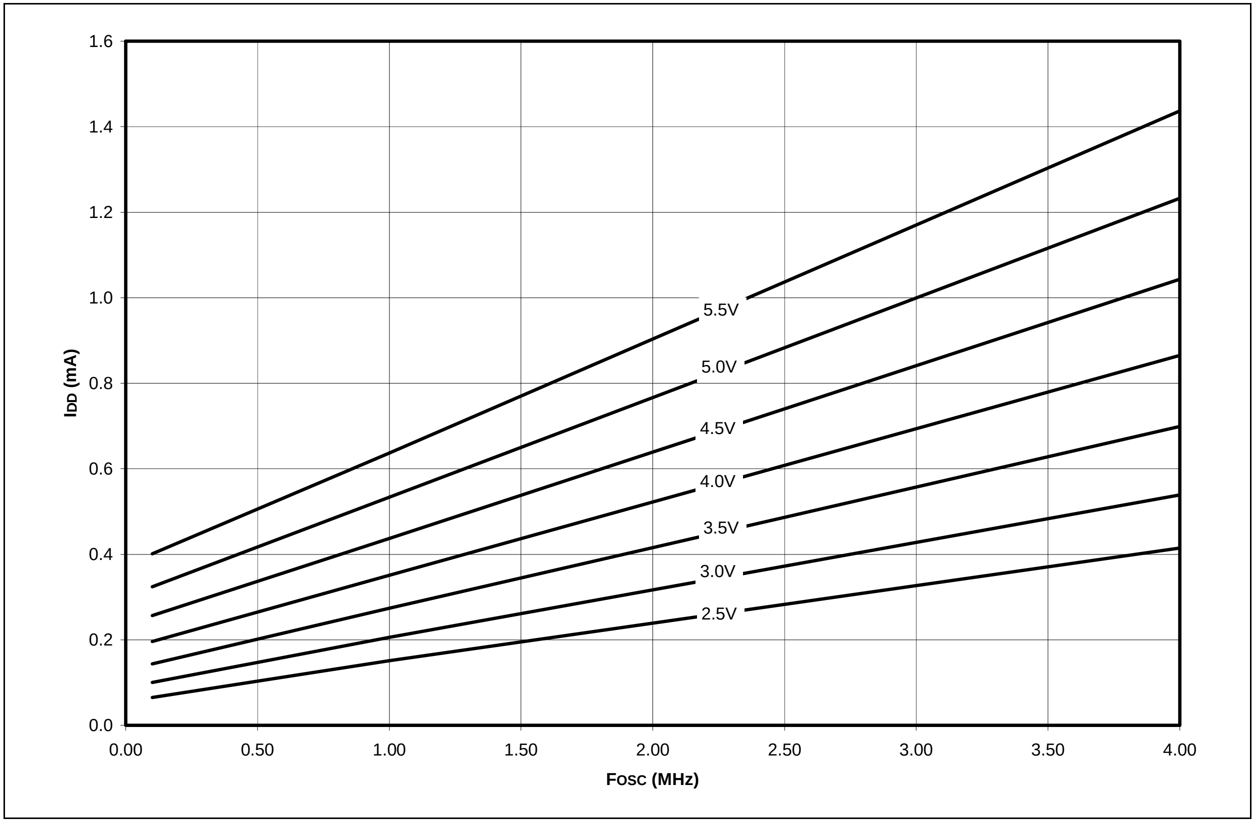


FIGURE 16-10: TYPICAL IDD VS. FOSC OVER VDD (ER MODE)

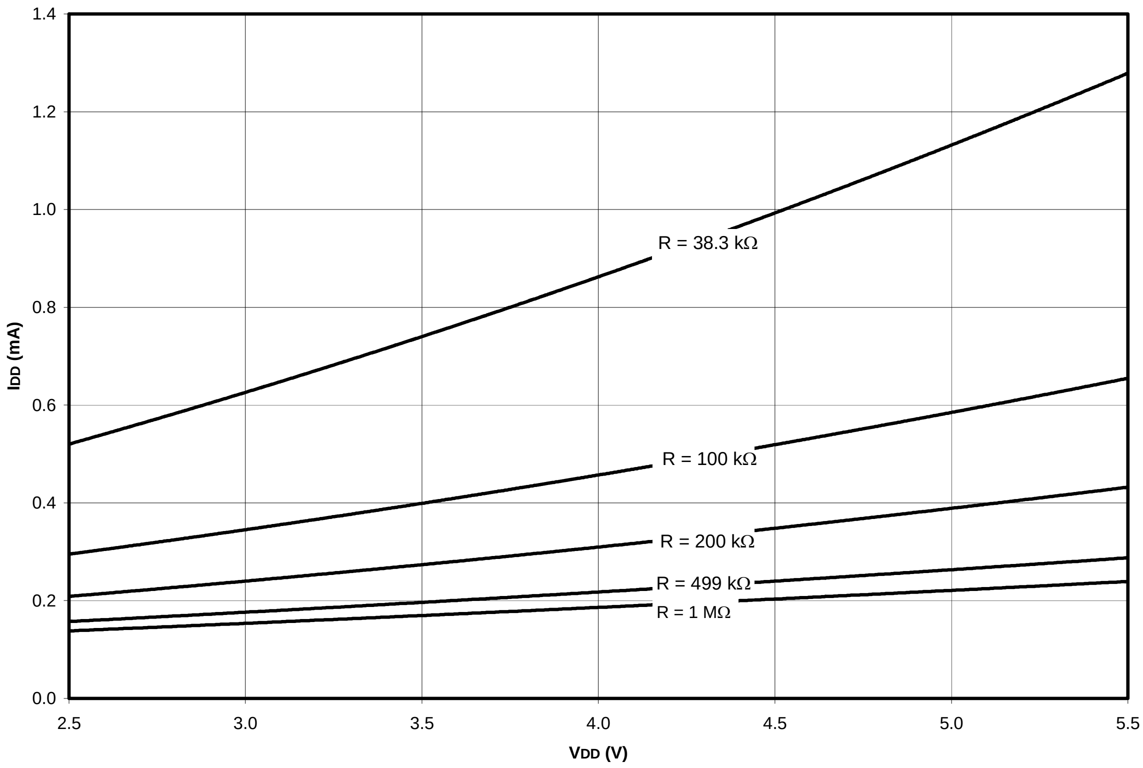


FIGURE 16-11: TYPICAL FOSC VS. VDD (ER MODE)

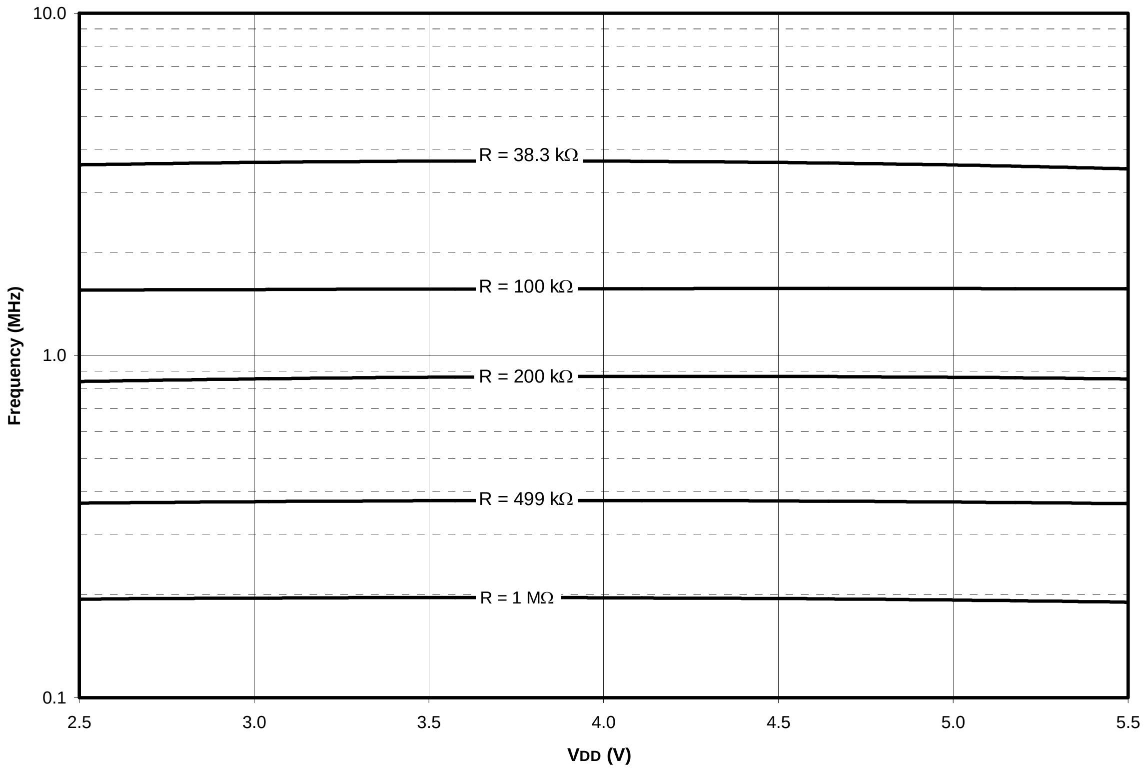


FIGURE 16-16: TYPICAL I_{DD} VS. V_{DD} (INTRC 4 MHz MODE)

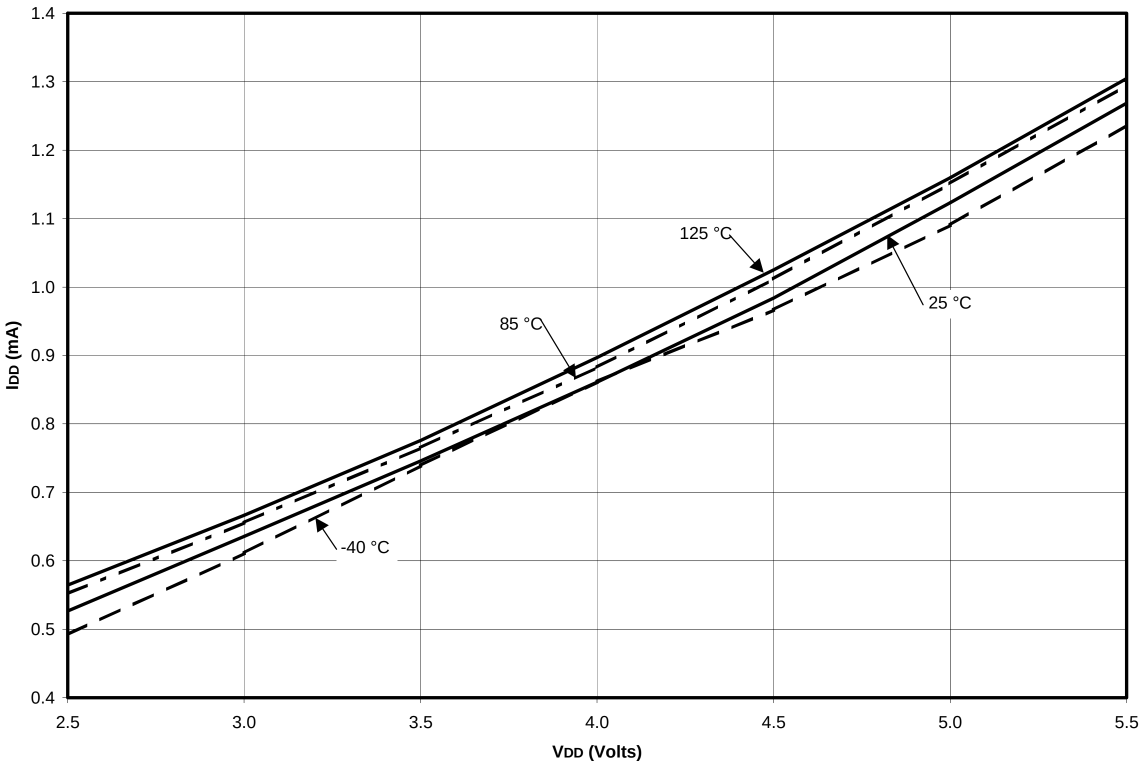


FIGURE 16-17: INTERNAL RC F_{OSC} VS. V_{DD} OVER TEMPERATURE (4 MHz)

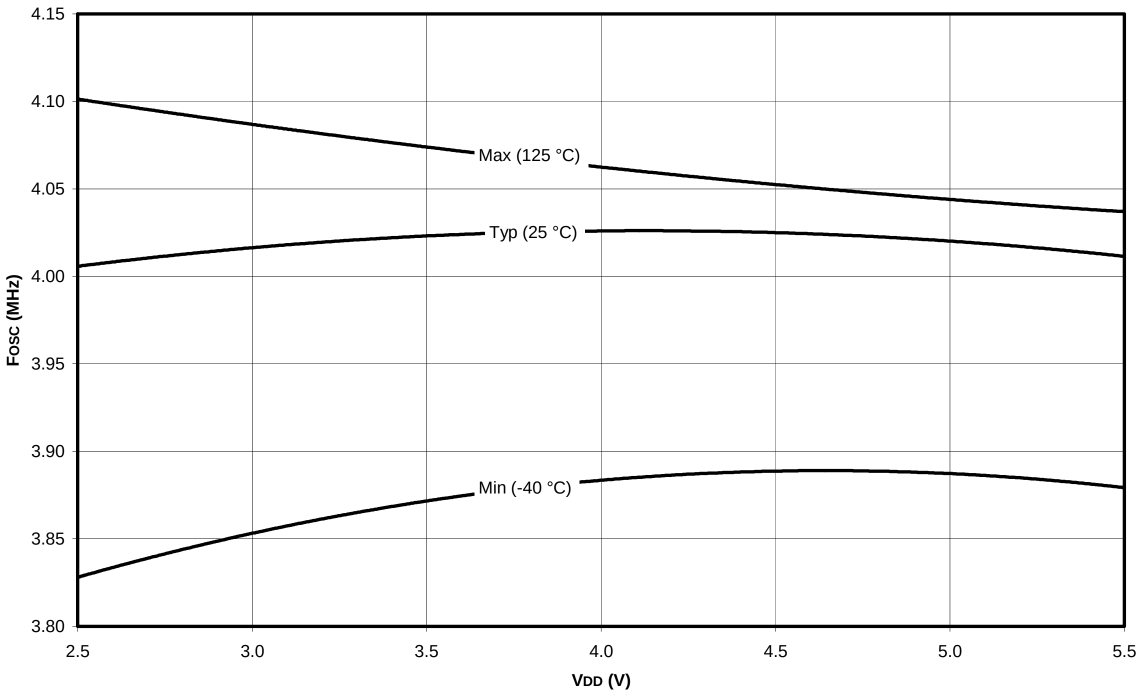


FIGURE 16-26: TYPICAL AND MAXIMUM ΔIBOR VS. VDD (-40°C TO +125°C) (VBOR = 4.5V)

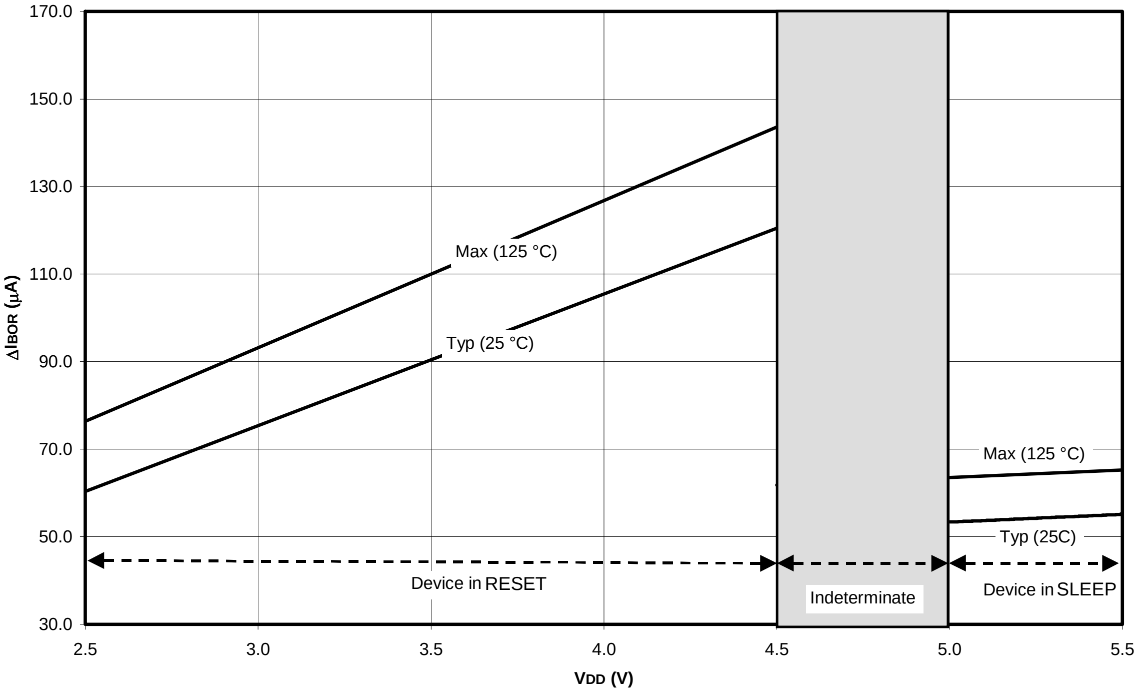


FIGURE 16-27: VOL VS. IOL (-40°C TO +125°C, VDD = 3.0V)